Final Product Change Notification

201506019F01

Issue Date: 04-Oct-2015
Effective Date: 17-Jan-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online

Change Category

[ ] Wafer Fab process	[ ] Assembly Process	[ ] Product Marking	[ ] Design
[ ] Wafer Fab materials	[X] Assembly Materials	[ ] Electrical spec./Test coverage	[ ] Mechanical Specification
[ ] Wafer Fab location	[ ] Assembly Location	[ ] Test Location	[ ] Packing/Shipping/Labeling

Change of bond wire from Au to Cu in SOT363 package

Details of this Change

Scheduled changes affect product types in SOT363 (SC-88) package only.

The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons only.

Old product: wire material is Au
Changed product: wire material is Cu or Au

The design and materials of all other components will remain unchanged: die, die attach, mold compound, and lead frame. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request
Latest sample request date for PCN samples is 27-Oct-2015.

Production

Planned first shipment 11-Jan-2016

Impact

No impact to the products' functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201003008F	26-Mar-2010		Change of bond wire material from gold to copper in SOT23 package
201204012F01	12-May-2012	10-Aug-2012	Change of bond wire material from gold to copper in SOT23 package
201506019A	05-Aug-2015		Change of bond wire from Au to Cu in SOT363 package

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 03-Nov-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support

e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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